

Title (en)

THERMOPLASTIC MOULDING MATERIALS

Title (de)

THERMOPLASTISCHE FORMMASSEN

Title (fr)

MATIERES MOULABLES THERMOPLASTIQUES

Publication

EP 1086177 A1 20010328 (DE)

Application

EP 99914568 A 19990406

Priority

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- EP 9902318 W 19990406

Abstract (en)

[origin: DE19817218A1] Use of polyisobutylene to improve the flow and extrusion characteristics of thermoplastic molding materials based on acrylic elastomer core/hard styrene shell graft polymer particles, styrene resin and styrene-butadiene resin. Thermoplastic molding materials comprising: (A) 20-98 wt.% of a particulate graft copolymer with (a1) 30-90 wt.% of a rubbery core of (a1i) 80-99.99 wt.% of a (C1-C10 alkyl)esters of acrylic acid, (a1ii) 0.01-20 wt.% of at least one crosslinking monomer and (a1iii) 0-19.99 wt.% of one or more further monomers, (a2) 10-70 wt.% of a grafted shell of (a2i) 50-100 wt.% of a styrene compound of formula (I), (a2ii) 0-50 wt.% of at least one mono-ethylenically unsaturated nitrile compound and (a2iii) 0-40 wt.% of one or more further monomers; R<1> and R<2> = H or 1-8 C alkyl; n = 0, 1, 2 or 3 (B) 0.5-78.5 wt.% of a thermoplastic polymer of (b1) 50-100 wt.% of a styrene compound of formula (I) above, (b2) 0-50 wt.% of at least one monoethylenically unsaturated nitrile compound and (b3) 0-40 wt.% of one or more further monomers; (C) 1-79 wt.% of a copolymer of (c1) 30-90 wt.% styrene and/or alpha -methylstyrene, (c2) 10-70 wt.% butadiene and (c3) 0-30 wt.% of one or more further monomers, in which the olefinic double bonds are completely or almost completely hydrogenated; and (D) 0.5-30 wt.% of a copolymer of (d1) 50-100 wt.% isobutene and (d2) 0-50 wt.% of one or more further monomers.

IPC 1-7

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IPC 8 full level

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